# onsemi

Initial Product/Process Change Notification Document #:IPCN25839X Issue Date:13 Dec 2023

Title of Change:	Transfer of Assembly and Test operation of IC DPAK-5 package (Case outline 936A-02) from onsemi Seremban, Malaysia to Good-Ark Electronics Co.,Itd, China		
Proposed First Ship date:	01 Oct 2024 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or Milos.Dvorak@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >		
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code.		
Change Category:	Assembly Change, Test Change		
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	

None
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### Description and Purpose:

This Initial Notification announces to customers that onsemi plans to Transfer Assembly and Test operations of the DPAK-5 package (Case Outline 936A-02) products from onsemi Seremban, Malaysia to Good-Ark Electronics Co., ltd, (Suzhou), China.

Good-Ark, China

	From	То	
Assembly / Test Site	onsemi, Seremban, Malaysia	Good-Ark Electronics Co., ltd, Suzhou, China	
Die Attach	Pb95Sn5	Pb92.5Sn5Ag2.5	
Mold Compound	EME G600	G700HF	

There is no product marking change as a result of this change.

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### **Qualification Plan:**

**QV DEVICE NAME:** NCV57302DSADJR4G **RMS:** S91762, S93928, S93929 **PACKAGE:** D2PAK 5LD EG

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=104°C, 100 % max rated Vcc	1008 hrs
Early Life Failure Rate	JESD22-A108	Ta=104°C, 100 % max rated Vcc	48 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C, mounted form air to air	500 cyc
Power Temperature Cycling	JESD22 A105	Tj= -40°C to +125°C, bias	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	110°C, 85% RH, 18.8psig, bias	528 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec	
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B120		

Estimated date for qualification completion: 1 March 2024

#### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal.** 

Part Number	Qualification Vehicle
NCP59302DSADJR4G	NCV57302DSADJR4G
NCP59152DSADJR4G	NCV57302DSADJR4G
NCP57152DSADJR4G	NCV57302DSADJR4G
NCP5663DSADJR4G	NCV57302DSADJR4G
LM2931ACD2TR4G	NCV57302DSADJR4G